

# **Description**

The VSM3417 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a load switch or in PWM applications.

#### **General Features**

•  $V_{DS} = -12V, I_{D} = -4.4A$ 

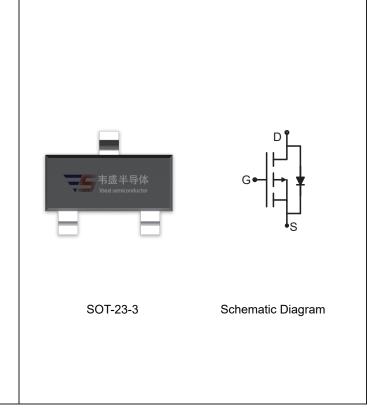
 $R_{DS(ON)}$  < 56m $\Omega$  @  $V_{GS}$ =-2.5V

 $R_{DS(ON)}$  < 40m $\Omega$  @  $V_{GS}$ =-4.5V

- High power and current handing capability
- Lead free product is acquired
- Surface mount package

## **Application**

- PWM applications
- Load switch
- Power management



## **Package Marking And Ordering Information**

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
VSM3417-S2	VSM3417	SOT-23-3	Ø180mm	8 mm	3000 units

#### Absolute Maximum Ratings (TA=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	VDS	-12	V	
Gate-Source Voltage	Vgs	±12	V	
Drain Current -Continuous	I <sub>D</sub>	-4.4	Α	
Drain Current -Pulsed (Note 1)	I <sub>DM</sub>	-15	Α	
Maximum Power Dissipation	P <sub>D</sub>	1.8	W	
Operating Junction and Storage Temperature Range	$T_{J}, T_{STG}$	-55 To 150	℃	

#### **Thermal Characteristic**

Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	69	°C/W
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# Electrical Characteristics (T<sub>A</sub>=25 °C unless otherwise noted)

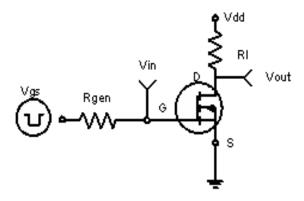
Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics	·		•	•		
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	BV <sub>DSS</sub> V <sub>GS</sub> =0V I <sub>D</sub> =-250µA			-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-12V,V <sub>GS</sub> =0V	-	-	-1	μΑ
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±12V,V <sub>DS</sub> =0V	-	-	±100	nA
On Characteristics (Note 3)	•			•		
Gate Threshold Voltage	$V_{GS(th)}$	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =-250μA	-0.45	-0.7	-1.0	V
D : 0	_	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-4.4 A	-	27	40	
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-3A	- 40		56	mΩ
Forward Transconductance	<b>g</b> FS	V <sub>DS</sub> =-5V,I <sub>D</sub> =-4.4A	-	6	-	S
Dynamic Characteristics (Note4)	1	1	Į.	l.		
Input Capacitance	C <sub>lss</sub>	\/ - C\/\/ -O\/	-	700	-	PF
Output Capacitance	C <sub>oss</sub>	$V_{DS}$ =-6V, $V_{GS}$ =0V, F=1.0MHz	-	280	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>	F=1.UIVIHZ	-	210	-	PF
Switching Characteristics (Note 4)	·		•	•		
Turn-on Delay Time	t <sub>d(on)</sub>		-	13	-	nS
Turn-on Rise Time	t <sub>r</sub>	$V_{DD}$ =-6 $V$ , $I_{D}$ =-4.4 $A$ ,	-	36	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>	$R_L$ =-1.2 $\Omega$ , $V_{GEN}$ =-4.5 $V$ , $R_g$ =1 $\Omega$	-	32	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	12	-	nS
Total Gate Charge	Qg	V 0V 1 4 4	-	8.1	-	nC
Gate-Source Charge	$Q_{gs}$	V <sub>DS</sub> =-6V,I <sub>D</sub> =-4.4	-	1.3	-	nC
Gate-Drain Charge	$Q_{gd}$	A,V <sub>GS</sub> =-4.5V	-	1.7	-	nC
Drain-Source Diode Characteristics	1	•	ı	ı		1
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =-4.4A	-	-	-1.2	V
Diode Forward Current (Note 2)	Is		-	-	4.4	Α

## Notes:

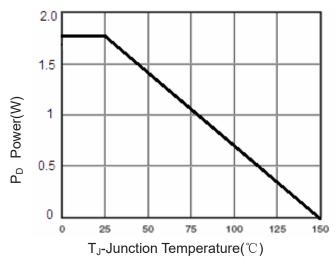
- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board,  $t \le 10$  sec.
- **3.** Pulse Test: Pulse Width ≤  $300\mu$ s, Duty Cycle ≤ 2%.
- **4.** Guaranteed by design, not subject to production



## **Typical Electrical and Thermal Characteristics**



**Figure 1:Switching Test Circuit** 



**Figure 3 Power Dissipation** 

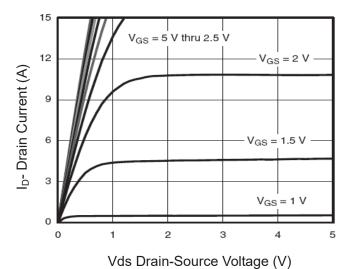


Figure 5 Output Characteristics

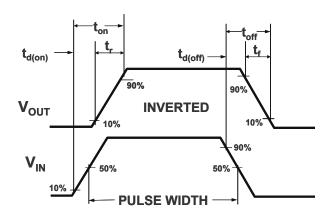
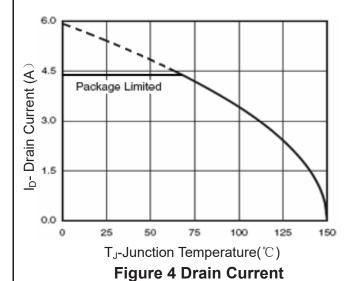


Figure 2:Switching Waveforms



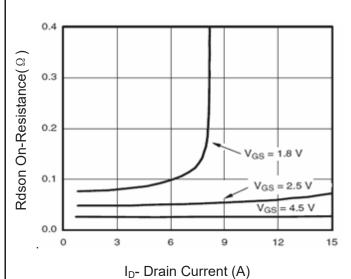
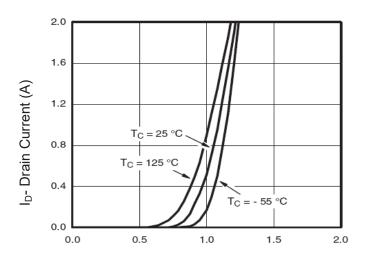
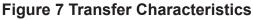


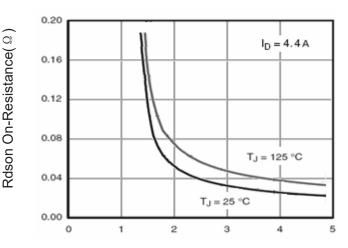
Figure 6 Drain-Source On-Resistance





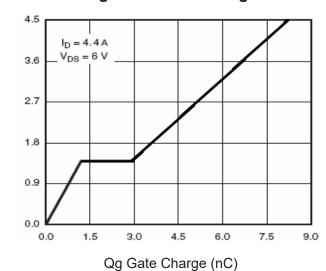
Vgs Gate-Source Voltage (V)





Vgs Gate-Source Voltage (V)

Figure 9 Rdson vs Vgs



Vgs Gate-Source Voltage (V)

Figure 11 Gate Charge

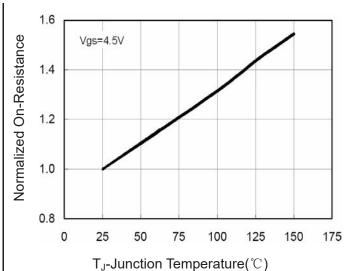
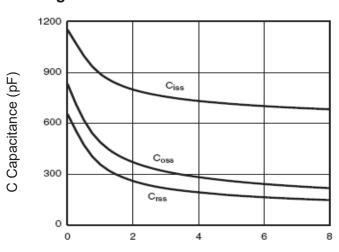
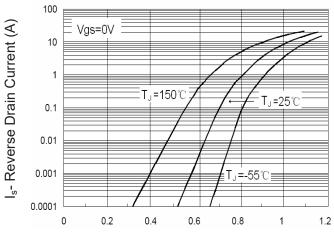


Figure 8 Drain-Source On-Resistance



Vds Drain-Source Voltage (V)

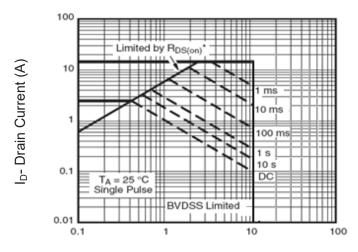
Figure 10 Capacitance vs Vds



Vsd Source-Drain Voltage (V)

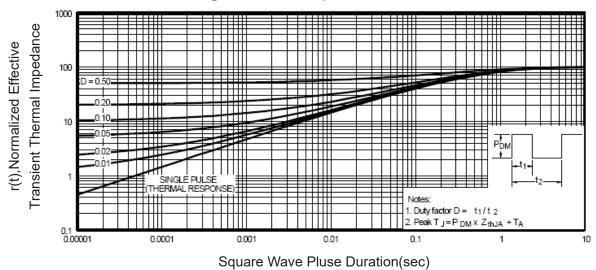
Figure 12 Source- Drain Diode Forward





Vds Drain-Source Voltage (V)

Figure 13 Safe Operation Area



**Figure 14 Normalized Maximum Transient Thermal Impedance**